



BCR2PM-12RE

Triac

Low Power Use

REJ03G1468-0100

Rev.1.00

Jul 31, 2006

Features

- $I_{T(RMS)}$: 2 A
- V_{DRM} : 600 V
- I_{RGT}, I_{RGT} : 10 mA
- Insulated Type
- Planar Passivation Type
- The product guaranteed maximum junction temperature 150°C.

Outline

RENESAS Package code: PRSS0003AA-B
(Package name: TO-220F(2))



1. T_1 Terminal
2. T_2 Terminal
3. Gate Terminal

Applications

Electric rice cooker, electric pot, and controller for other heater

Precautions on Usage

When the BCR2PM-12RE is used, do not attach the heat radiating fin.

Maximum Ratings

Parameter	Symbol	Voltage class	Unit
		12	
Repetitive peak off-state voltage ^{Note1}	V_{DRM}	600	V
Non-repetitive peak off-state voltage ^{Note1}	V_{DSM}	720	V

BCR2PM-12RE

Parameter	Symbol	Ratings	Unit	Conditions
RMS on-state current	$I_T (RMS)$	2	A	Commercial frequency, sine full wave 360° conduction
Surge on-state current	I_{TSM}	10	A	60Hz sinewave 1 full cycle, peak value, non-repetitive
I^2t for fusing	I^2t	0.41	A ² s	Value corresponding to 1 cycle of half wave 60Hz, surge on-state current
Peak gate power dissipation	P_{GM}	1	W	
Average gate power dissipation	$P_{G(AV)}$	0.1	W	
Peak gate voltage	V_{GM}	6	V	
Peak gate current	I_{GM}	1	A	
Junction temperature	T_j	– 40 to +150	°C	
Storage temperature	T_{stg}	– 40 to +150	°C	
Mass	—	2.0	g	Typical value

Notes: 1. Gate open.

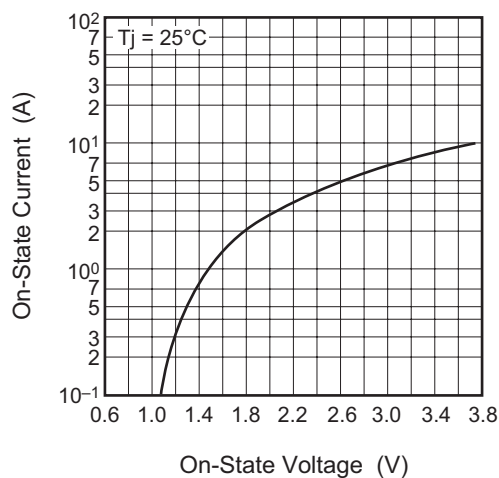
Electrical Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test conditions
Repetitive peak off-state current	I_{DRM}	—	—	1.0	mA	$T_j = 150^\circ\text{C}$, V_{DRM} applied
On-state voltage	V_{TM}	—	—	1.6	V	$T_j = 25^\circ\text{C}$, $I_{TM} = 1.5\text{ A}$, Instantaneous measurement
Gate trigger voltage ^{Note2}	II	V_{RGTI}	—	—	2.0	$T_j = 25^\circ\text{C}$, $V_D = 6\text{ V}$, $R_L = 6\ \Omega$, $R_G = 330\ \Omega$
	III	V_{RGTIII}	—	—	2.0	
Gate trigger current ^{Note2}	II	I_{RGTI}	—	—	10	$T_j = 25^\circ\text{C}$, $V_D = 6\text{ V}$, $R_L = 6\ \Omega$, $R_G = 330\ \Omega$
	III	I_{RGTIII}	—	—	10	
Gate non-trigger voltage	V_{GD}	0.1	—	—	V	$T_j = 150^\circ\text{C}$, $V_D = 1/2\ V_{DRM}$
Thermal resistance	$R_{th(j-a)}$	—	—	45	°C/W	Junction to ambient, Natural convection

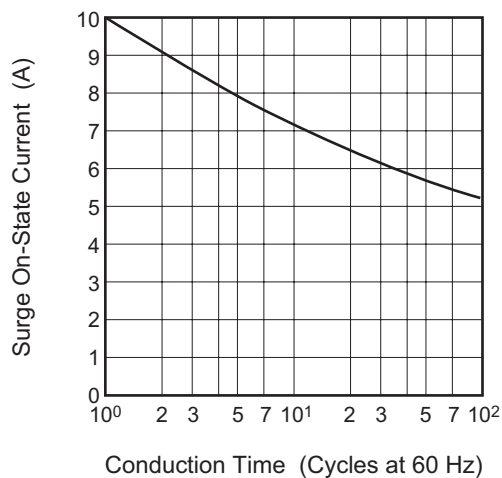
Notes: 2. Measurement using the gate trigger characteristics measurement circuit.

Performance Curves

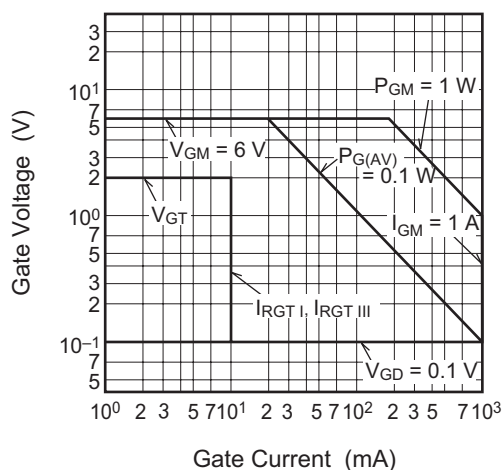
Maximum On-State Characteristics



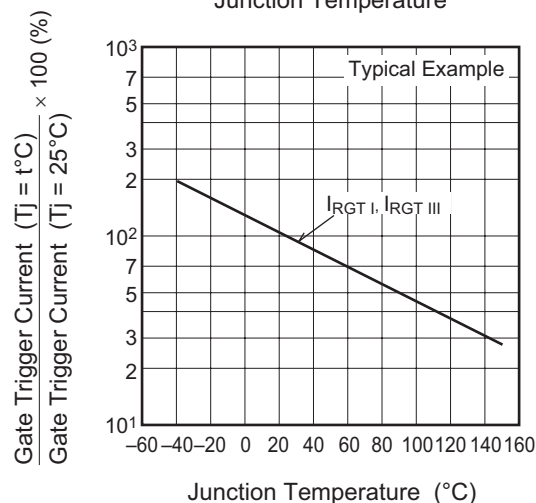
Rated Surge On-State Current



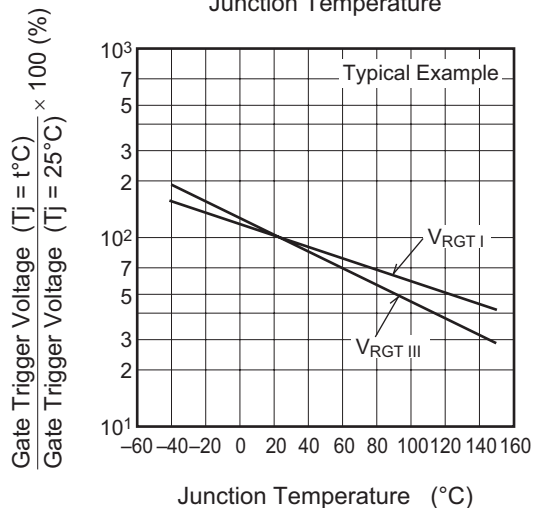
Gate Characteristics (II and III)



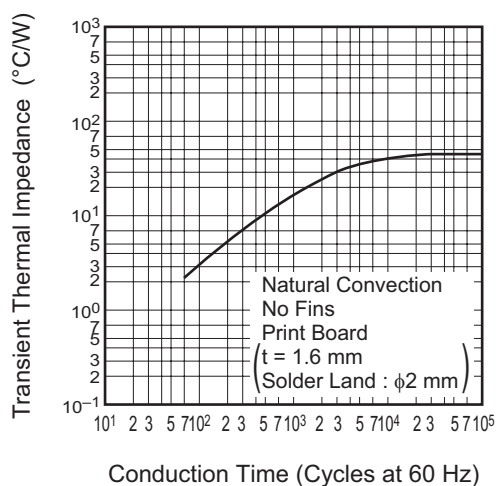
Gate Trigger Current vs. Junction Temperature



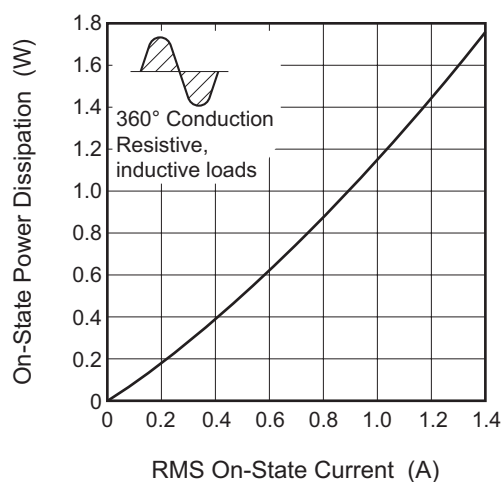
Gate Trigger Voltage vs. Junction Temperature



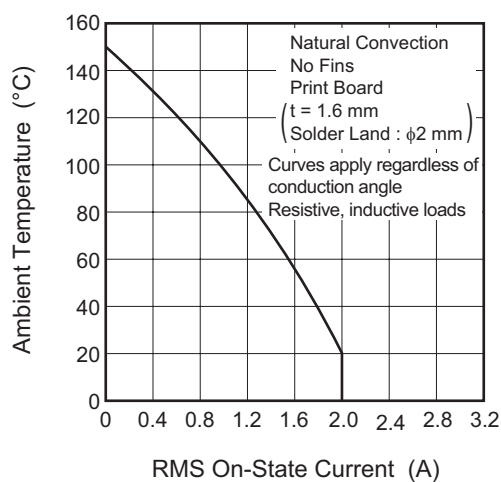
Maximum Transient Thermal Impedance Characteristics (Junction to ambient)



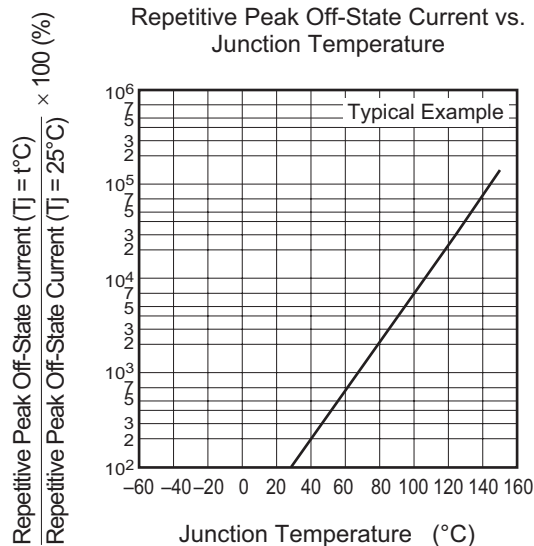
Maximum On-State Power Dissipation



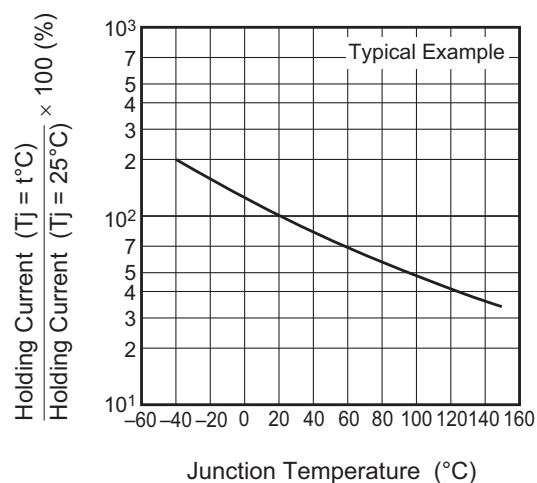
Allowable Ambient Temperature vs. RMS On-State Current



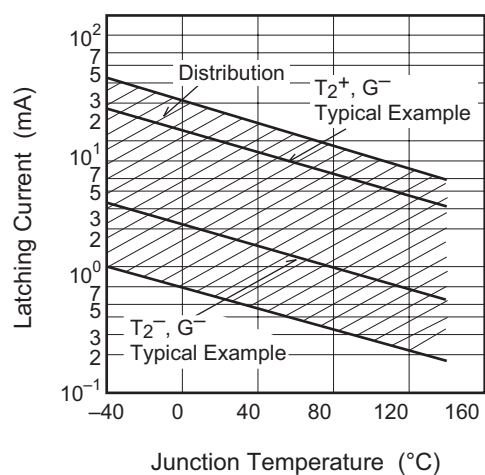
Repetitive Peak Off-State Current vs. Junction Temperature



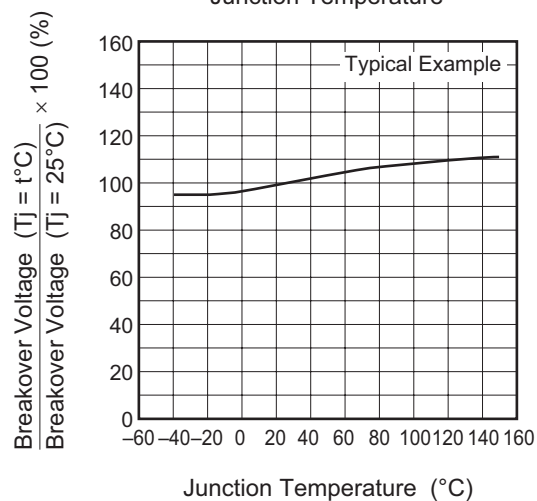
Holding Current vs. Junction Temperature

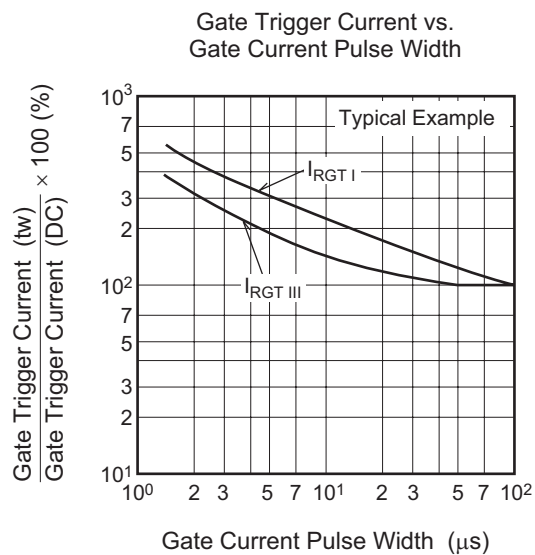
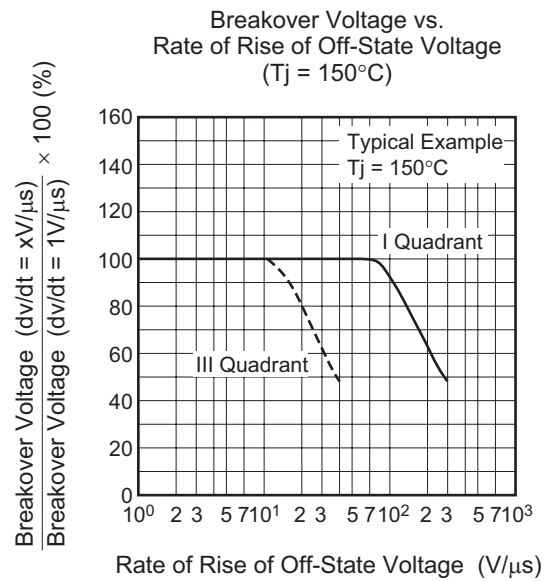
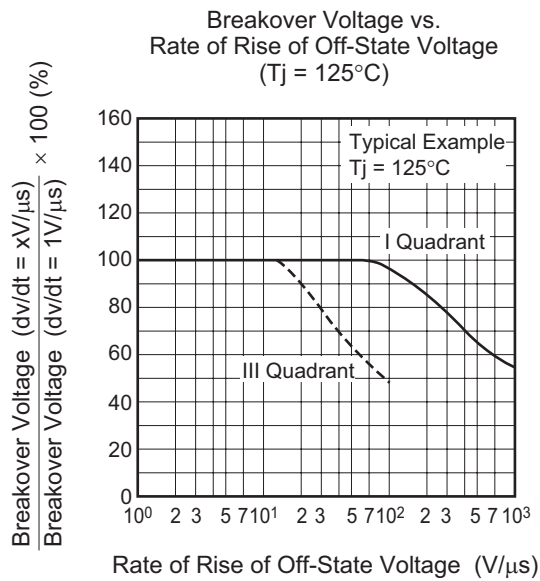


Latching Current vs. Junction Temperature

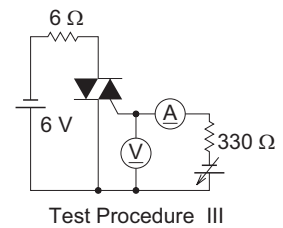
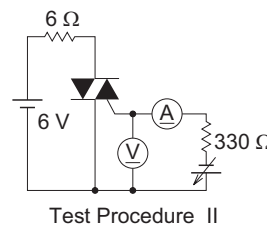


Breakover Voltage vs. Junction Temperature





Gate Trigger Characteristics Test Circuits



Package Dimensions

Package Name	JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]	Unit: mm
TO-220F(2)	SC-67	PRSS0003AA-B	—	2.0g	

The drawing shows the mechanical dimensions of the BCR2PM-12RE package. The top view shows a rectangular body with a central circular feature. Dimensions include a total width of 10.5Max, a central width of 5.2, a height of 17, a central hole diameter of $\phi 3.2 \pm 0.2$, and a body height of 8.5. The side view shows a total height of 13.5Min, a body height of 5.0, a lead height of 1.2, and a lead thickness of 0.8. The bottom view shows a total width of 2.54 and a lead width of 2.6. A detail view shows a lead thickness of 0.5 and a lead width of 2.6.

Order Code

Lead form	Standard packing	Quantity	Standard order code	Standard order code example
Straight type	Vinyl sack	100	Type name	BCR2PM-12RE
Lead form	Plastic Magazine (Tube)	50	Type name – Lead forming code	BCR2PM-12RE-A8

Note : Please confirm the specification about the shipping in detail.

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